Surface Mount Ultrafast Power Rectifier

Ideally suited for high voltage, high frequency rectification, or as free wheeling and protection diodes in surface mount applications where compact size and weight are critical to the system.

Features

- Small Compact Surface Mountable Package with J-Bend Leads
- Rectangular Package for Automated Handling
- High Temperature Glass Passivated Junction
- Low Forward Voltage Drop (1.2 V Max @ 2.0 A, $T_J = 150^{\circ}C$)
- SURA8 Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable*
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

Mechanical Characteristics:

- Case: Epoxy, Molded
- Weight: 70 mg (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Polarity: Polarity Band Indicates Cathode Lead
- ESD Protection:
 - Human Body Model > 4000 V (Class 3)
 - Machine Model > 400 V (Class C)



ON Semiconductor®

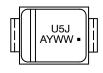
www.onsemi.com

ULTRAFAST RECTIFIER 2 AMPERES, 600 VOLTS



SMA CASE 403D PLASTIC

MARKING DIAGRAM



U5J = Device Code

A = Assembly Location**

Y = Year

- WW = Work Week
- = Pb–Free Package

** The Assembly Location Code (A) is front side optional. In cases where the Assembly Location is stamped in the package bottom (molding ejecter pin), the front side assembly code may be blank.

ORDERING INFORMATION

Device	Package	Shipping [†]
MURA260T3G	SMA (Pb-Free)	5,000/Tape & Reel
SURA8260T3G*	SMA (Pb-Free)	5,000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	600	V
Average Rectified Forward Current @ $T_L = 145^{\circ}C$ @ $T_L = 110^{\circ}C$	I _{F(AV)}	1.0 2.0	A
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I _{FSM}	30	A
Operating Junction Temperature Range	TJ	-65 to +175	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction-to-Lead ($T_L = 25^{\circ}C$) (Note 1)	Psi _{JL} (Note 2)	24	°C/W
Thermal Resistance, Junction-to-Ambient (Note 1)	R _{θJA}	216	

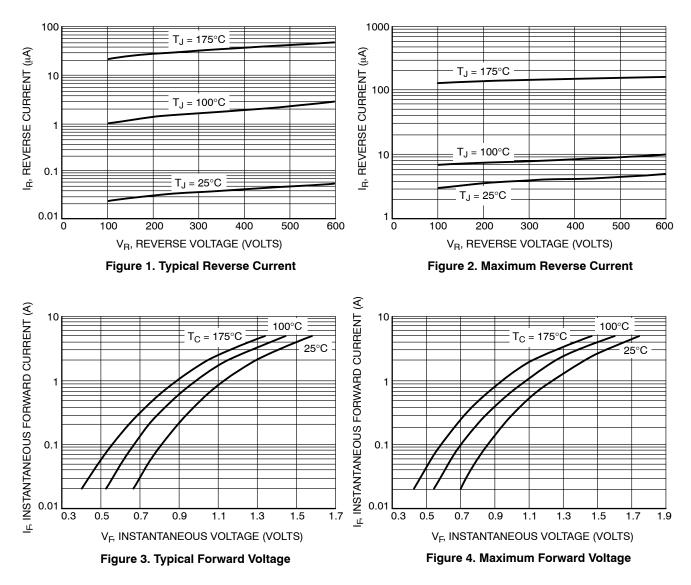
1. Rating applies when surface mounted on the minimum pad size recommended, PC Board FR-4.

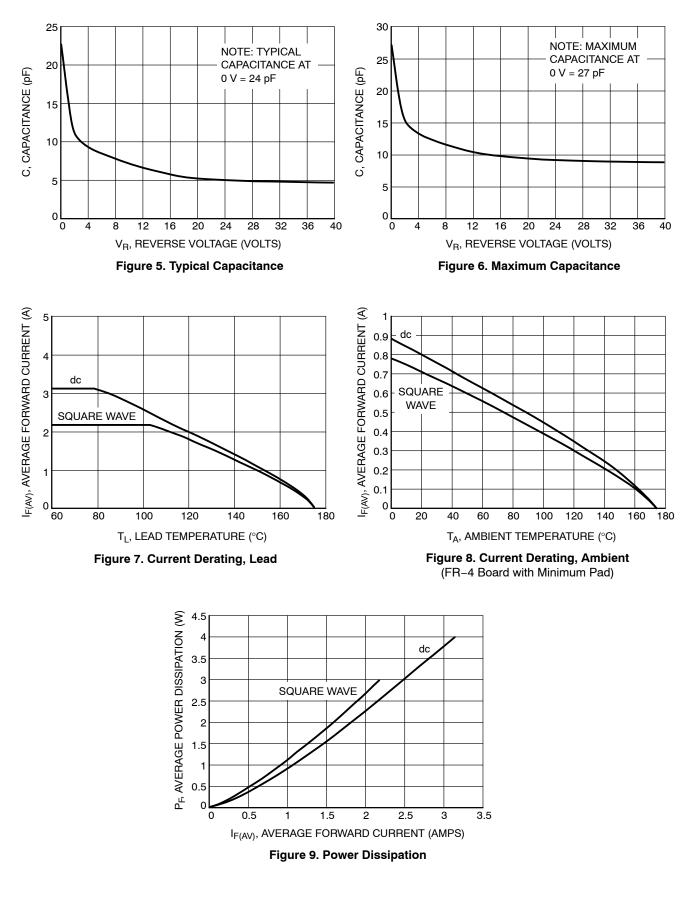
2. In compliance with JEDEC 51, these values (historically represented by $R_{\theta JL}$) are now referenced as Psi_{JL} .

ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Мах	Unit
	v _F	1.45 1.20	V
Maximum Instantaneous Reverse Current (Note 3) (Rated DC Voltage, $T_J = 25^{\circ}C$) (Rated DC Voltage, $T_J = 150^{\circ}C$)	İR	5.0 150	μΑ
Maximum Reverse Recovery Time (i _F = 1.0 A, di/dt = 50 A/μs)	t _{rr}	75	ns

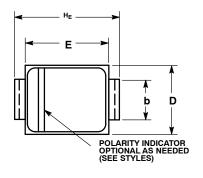
3. Pulse Test: Pulse Width = 300 μ s, Duty Cycle \leq 2.0%.





PACKAGE DIMENSIONS

SMA CASE 403D ISSUE H

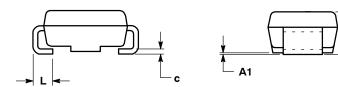


NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

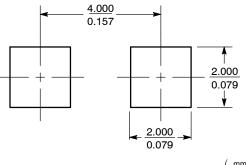
2. CONTROLLING DIMENSION: INCH.

3. DIMENSION b SHALL BE MEASURED WITHIN DIMENSION L.

	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	1.97	2.10	2.20	0.078	0.083	0.087	
A1	0.05	0.10	0.20	0.002	0.004	0.008	
b	1.27	1.45	1.63	0.050	0.057	0.064	
С	0.15	0.28	0.41	0.006	0.011	0.016	
D	2.29	2.60	2.92	0.090	0.103	0.115	
E	4.06	4.32	4.57	0.160	0.170	0.180	
HE	4.83	5.21	5.59	0.190	0.205	0.220	
L	0.76	1.14	1.52	0.030	0.045	0.060	



SOLDERING FOOTPRINT*



SCALE 8:1 $\left(\frac{\text{mm}}{\text{inches}}\right)$

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at <u>www.onsemi.com/site/pdf/Patent-Marking.pdf</u>. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor "Typical" parameters which may be provided in ON Semiconductor dates sheets and/or application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights or others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor hardles against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors h

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800–282–9855 Toll Free USA/Canada Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910

Japan Customer Focus Center Phone: 81–3–5817–1050 ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative